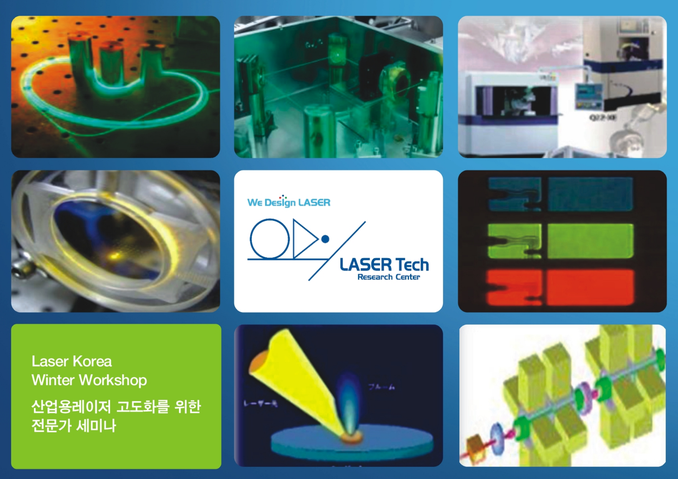
2023 (13th)
Laser Korea Congress



| 일자 : 2023. 1. 12.(목) ~ 1. 13.(금)
| 장소 : 김대중컨벤션센터 4층 컨벤션홀
| 주관 : 한국레이저가공학회, 나노융합산업연구조합
| 후원 : OSK 사단법인 한국광학회 Optical Society of Korea, GJTO 광주관광재단, 산업용레이저기업협의회, KOFST 한국과학기술단체총연합회, 광주전남지역연합회

Program

12 (Thursday)

Chair : Dr. Swook Hann (KOPTI, Korea)

Recent issues in Laser Industries

12:00-14:00	Registration and Welcome Exhibition
14:00-14:30	Laser Drilling and Real-time Monitoring of Via Holes in PCB (Dr. Stefan Janssen, LGE PRI, Korea)
14:30-15:00	Large Area, short wavelength laser processing with high depth control (Burkhard Fechner, Max Fischer, Ralph Delmdahl, Coherent LaserSystems GmbH & Co. KG, Germany)
15:00-16:00	Exhibition
16:00-16:30	Laser beam shaping increases welding speed of thin foil (Dr. Eyal Shekel, CEO, Civan Lasers, Israel)
16:30-17:00	High Brightness Green Laser for Cu/Al thin metal processing (Trumpf Laser -und Systemtechnik GmbH, Germany)
17:00-17:30	fs-high power laser and their applications (Dr. Martynas Barkauskas, CEO, Light Conversion, Lithuania)
17:30-18:00	Advanced Industrial Applications of Ultrafast Fiber Lasers (Dr. Tony Karam, Product Manager of Ultrafast Laser, IPG Photonics, USA)
18:00-19:00	Honor Award and Congress Dinner
20:00-21:00	Welcome Reception (Speakers Meeting)

13 (Friday)

Chair : Dr. Friedrich Bachmann (Friba-Lasernet, Germany)

Emerging Laser Industrial Applications

09:00-10:00	Registration and Exhibition
10:00-10:30	The MOONRISE payload - a first step towards additive manufacturing on the Moon (Dr. Joerg Neumann, Head of Laser Development Department, LZH, Germany)
10:30-11:00	High power fiber laser for Laser Additive Manufacturing (Robert Martinsen, CTO, nLight, USA)
11:30-12:00	Commercial Laser 3D printing systems for Aerospace and medical applications (Dr. Seokjin Shin, CTO, Insstek, Korea)
12:00-13:00	Lunch
13:00-13:30	Exhibition

Chair : Dr. Burkhard Fechner (Coherent Laser System GmbH)

13:30-14:00	High speed laser PCB processing (KLA-Orbotech, under contact)
14:00-14:30	Advanced Laser PCB manufacturing by wet and dry processing (TBU, LPKF, Germany)
14:30-15:00	High precision laser PCB processing by high power fs and UV laser (Goeff Lott, MVP Product Engineering Manager, MKS-ESI, USA)
15:00-15:30	Exhibition
15:30-16:00	Applications of Advanced Laser Reflow Packaging Technology in Semiconductor, Display, EV Cars Fields (N.S. Kim, CTO, Laserssel, Korea)
16:00-16:30	Laser assisted bonding for semiconductor production by compact laser sources and tailored optics technologies, TBU, Laserline, Germany
16:30-17:00	Ending remarks

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